

Final Program

















Université du Littoral - Côte d'Opale (ULCO) Bâtiment des Darses 189B, Avenue Maurice Schumann 59140 Dunkerque

http://9th-thz-days.univ-littoral.fr

Program

Monday

12H00 : Welcome / registration

13H30 : Opening

Brief information (C. Sirtori, J. Mangeney)

14H00: Session 1 - Sources (THz and MIR)

Chairman: T. Yasui

14H00 : M1 - S. Houver

«Multi-THz Sideband Generation on an optical telecom carrier at room

temperature»

14H30 : M2 - F. Joint

«Development of low power consumption quantum cascade lasers at 2.7

THz for compact and ultra-sensitive heterodyne detectors»

14H45 : M3 - S. Barbieri

«5ps-long terahertz pulses from an active mode-locked quantum cascade

laser»

15H00 : M4 - R. Wang

«DFB laser array in the 2.3 µm wavelength range on a silicon photonic in-

tegrated circuit»

15H15 : M5 - K. Maussang

«Monolithic Echo-less Photoconductive Switches for High-Resolution Te-

rahertz Time-domain Spectroscopy»

15H30 : *** Coffee break ***

DFB laser array in the 2.3 μ m wavelength range on a silicon photonic integrated circuit

<u>Ruijun Wang^{1,2}</u>, Stephan Sprengel³, Gerhard Boehm³, Roel Baets^{1,2}, Markus-Christian Amann³, Gunther Roelkens^{1,2}

The spectral range of 2.3 µm is of interest for gas sensing as many important gases have strong absorption lines in this wavelength range, including NH₃, CH₄, CO, C₂H₂ and HF. Besides, it also attracts interest in bio-sensing applications, such as non-invasive blood glucose measurements. Recently developed short-wave infrared and mid-infrared silicon photonic integrated circuits offer great potential to realize miniature gas and bio-sensors on silicon photonics chips. Low-loss and compact mid-infrared circuits can be fabricated in a CMOS pilot line, which enables high performance passive components such as (de)multiplexer. A compact silicon photonics spectroscopic sensor requires an integrated light source on silicon. However, the development of silicon photonics light sources above 2 µm wavelength still lags behind.

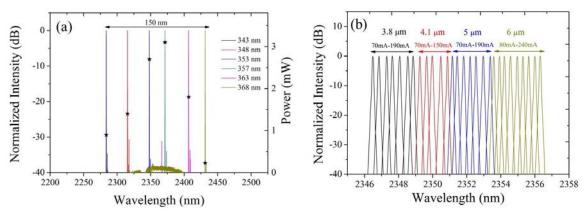


Fig.1. Heterogeneously integrated 2.3 µm III-V-on-silicon DFB lasers with different silicon grating pitchs (a) and device widths (b) in an array.

At Ghent University-IMEC, we developed a heterogeneous III-V-on-silicon platform for optical communication and sensing applications [1]. Here we report 2.3 µm range InP-based type-II DFB laser arrays heterogeneously integrated on a silicon photonic integrated circuit (PIC). An InP-based type-II epitaxial layer stack with "W"-shaped InGaAs/GaAsSb quantum wells is used as the gain medium and bonded to the silicon PIC. Detailed information of the device structure and fabrication process flow can be found in [2]. As shown in Fig. 1(a), the continuous wave (CW) operated DFB lasers can cover a broad wavelength range from 2.28 µm to 2.43 µm by varying the silicon grating pitch. By adjusting the laser device widths, a four wavelength DFB laser array with 10 nm continuous tuning is achieved as shown Fig. 1(b). In CW regime, the DFB laser can operate up to 25 °C and emits a maximum optical power of around 3 mW at 5 °C.

References

- [1] G. Roelkens et al., *Photonics*, 2 (2015) 969.
- [2] R. Wang et al., Appl. Phys. Lett., 109 (2016) 221111.

¹ Photonics Research Group, Ghent University-imec, Technologiepark-Zwijnaarde 15, 9052 Ghent, Belgium

² Center for Nano- and Biophotonics (NB-Photonics), Ghent University, Ghent, Belgium Walter Schottky Institut, Technische Universität München, Am Coulombwall 4, 85748
Garching, Germany